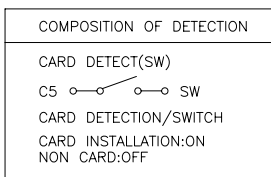



SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA



- NOTE:
- Material:
    - 1-1 Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
    - 1-2 Contact: Phosphor Bronze (C5210R-H, T=0.08±0.01mm)
    - 1-3 Cover: SUS304-H T=0.15±0.03mm
  - Plating:
    - 2-1 Contact terminal:
      - Contact area: Gold 1u" Min.
      - Solder area: Gold 0.8u" Min.
      - Underplating: Ni overall 50U" Min.
    - 2-2 Cover:
      - Underplating: Ni overall 30U" Min.
      - Solder area: Gold 0.8u" Min.
  - Specification:
    - 3-1. Current Rating :0.5A max.
    - 3-2. Contact Resistance: 50 mOhms max
    - 3-3. Insulation Resistance: 1000 MOhms min./500VDC
    - 3-4. Dielectric Withstanding Voltage: 500 V AC/1minute
    - 3-5. Operating Temperature: -40°C to +85°C
    - 3-6. Mating Cycles: 5000 Insertions
  - Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
  - Part Must Comply Taisol HF WD-3-1-091 Specification.
  - Recommending A Metal More Than 0.15mm Thick.  
Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.



## 深圳市华宇创精密电子有限公司

<b>TOLERANCE:</b> X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2'    X.X' ±0.5'	<b>DRAWN BY :</b>	<b>DATE :</b>	<b>PART NAME:</b>
	陈一鸣	2014-02-23	NANO SIM 1.5H SMT TYPE卡托式
UNIT: mm [inch] SCALE: 1:1    SIZE: A4	<b>CHECKED BY:</b>	<b>DATE :</b>	<b>PART NO.</b>
	马跃	2014-02-23	HVCW312-SIM07-150B
	<b>APPROVED BY:</b>	<b>DATE :</b>	<b>DRAW NO:</b>
	邱敏	2014-02-23	HVC-2206021023
			<b>SHEET NO.</b>
			1 OF 1